### CMPE 310 Systems Design and Programming

L6: Chapter 10 – Memory Interface



# L6 Objectives

- \* Explore Semiconductor memories
- \* Three main characteristics of memory devices
- \* Memory address decoding

### Semiconductor memories

Read Select

- \* Almost all systems contain two basic types:
  - \* ROM: Read-only memory
  - \* RAM: Read-Write memory
- \* Three Memory Characteristics:
  - \* IC Memory/ Chip Capacity
    - \* No. of bits that a chip can store
  - \* Memory Organization
    - \*  $2^x$  locations, x = no. of address pins
    - \* Each location contains y bits; y = no. of data pins
    - \* Chip contain 2x x y bits
  - \* Speed
    - \* Access time varies → IC technology used

# Example

- \* If you have a memory chip with 12 address pins and 8 data pins:
  - \* Memory organization
  - \* Chip capacity
- \* If you have a 512K chip with 8 data pins:
  - \* Memory organization
  - \* Number of address pins

### Memory Interface

#### **Memory Chips**

- \* The number of address pins is related to the number of memory locations.
  - \* Common sizes today are 1K to 1G locations.
  - \* Therefore, between 10 and 30 address pins are present.
- \* The data pins are typically **bi-directional in read-write memories.** 
  - \* The number of data pins is related to the size of the memory location.
  - \* For example, an 8-bit wide (byte-wide) memory device has 8 data pins.
  - \* Catalog listing of 1K X 8 indicate a byte addressable 8K bit memory with 10 address pins.

### Memory chips

#### **Memory Chips**

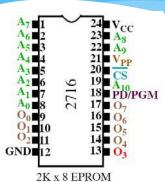
- \* Each memory device has at least one **chip select (CS) or chip enable** (**CE) or select (S) pin** that enables or select the memory device.
  - \* This enables read and/or write operations.
  - \* If more than one are present, then all must be o in order to perform a read or write.
- \* Each memory device has at least one control pin.
  - \* ROMs: an output enable (OE) or gate (G) connection is present.
    - \* The OE pin enables and disables a set of tristate buffers located in the device and must be active to read data.
  - \* RAMs: a read-write (R/W) or write enable (WE) and read enable (OE) are present.
    - \* For dual control pin devices, it must be hold true that both are not o at the same time to read or write data.

### Memory Interface

#### **Memory Chips**

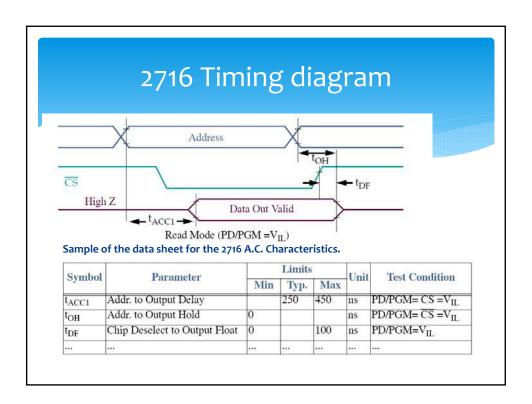
- \* ROM:
  - \* Non-volatile memory: Maintains its state when powered down.
  - \* There are several forms:
  - \* ROM: Factory programmed, cannot be changed. Older style.
  - \* PROM: Programmable Read-Only Memory.
    - \* Field programmable but only once. Older style.
  - \* EPROM: Erasable Programmable Read-Only Memory.
    - \* Reprogramming requires up to 20 minutes of high-intensity UV light exposure.
- \* Flash (EEPROM): Electrically Erasable Programmable ROM.
  - Also called EAROM (Electrically Alterable ROM) and NOVRAM (NOn-Volatile RAM).
  - \* Writing is much slower than a normal RAM.
  - \* Used to store setup information, e.g. video card on computer systems.
  - \* Can be used to replace EPROM for BIOS ROM memory.

### Intel 2716 EPROM



 $V_{pp}$  is used to program the device by applying 25V and pulsing PGM while holding  $\overline{CS}$  high

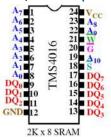
Pin(s)	Function
$\Lambda_0$ - $\Lambda_{10}$	Address
PD/PGM	Power down/Program
CS	Chip Select
00-07	Outputs



# Memory Interface

#### **SRAMs**

- \* Data is available as long as power supplied
  - \* Volatile Memory: as data is lost at power down
  - \* TI TMS 4016 SRAM (2K X 8):



Pin(s)	Function
A <sub>0</sub> -A <sub>10</sub>	Address
$DQ_0$ - $DQ_7$	Data In/Data Out
S (CS)	Chip Select
G (OE)	Read Enable
W (WE)	Write Enable

- \* Virtually identical to the EPROM with respect to the pinout.
- \* However, access time is faster (250ns).
- See the timing diagrams and data sheets in text.
- Modern SRAMs used for caches have access times as low as 10ns.

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#### Memory Interface **SRAMs** \* 62256 (32K X 8) RAM \* Access Time: 120-150 ns A 14 PIN FUNCTION 27 $A_6$ 25 IO<sub>0</sub>- IO<sub>7</sub> Data connections 24 A 5 Chip select 23 Output enable 22 WE Write enable 21 +5V Supply GND Ground 20 10 10 19 18 100 101 17 12 Other sizes IO<sub>2</sub> 16 GND \* 8KX8 \* 128K X 8 \* 256K X 8

### **DRAM**

- \* SRAMs are limited in size (up to 1M X 8).
- \* DRAMs are available in much larger sizes (up to 4G; 256 x 8, 4G x 1).
- \* Requires as little as 70 ns to access data
  - \* DRAMs MUST be refreshed (rewritten) every 2 to 4 ms
- \* This refresh is performed by a special circuit in the DRAM which refreshes the entire memory.
  - \* Refresh also occurs on a normal read or write.
- \* The large storage capacity of DRAMs make it impractical to add the required number of address pins.
  - \* Instead, the address pins are multiplexed.

### TI TMS4464 DRAM

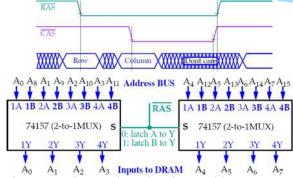


Pin(s)	Function
A <sub>0</sub> -A <sub>7</sub>	Address
DQ <sub>0</sub> -DQ <sub>3</sub>	Data In/Data Out
RAS	Row Address Strobe
CAS	Column Address Strobe
G	Output Enable
W	Write Enable

- ▼ Total chip capacity → 256K bits of data.
- \* It has **64K** addressable locations which means it needs 16 address inputs, but **it has only 8.** 
  - \* 16 address bits can be forced into eight address pins in two 8-bit increments
  - The row address (A<sub>0</sub> A<sub>7</sub>) are placed on the address pins and strobed into a set of internal latches by RAS
  - \* The column address  $(A_8 A_{15})$  is then strobed in using CAS

### TI TMS4464 DRAM timing diagram

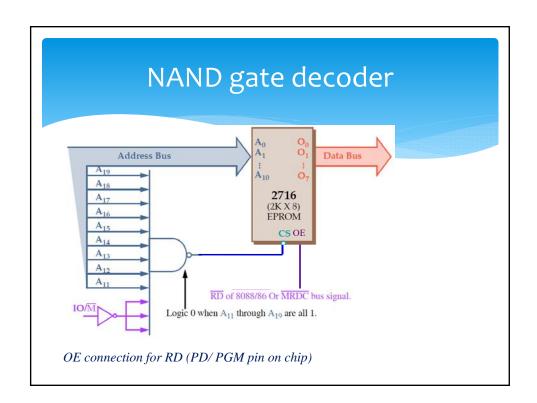
16-bit address in the internal latches, which addresses the contents of one of the 4-bit memory locations.



- \* Multiplexers used to strobe col and row addresses into the 8 address pins
- \* RAS signal strobes the row address into the DRAM and selects which part of the address is applied to the address inputs.

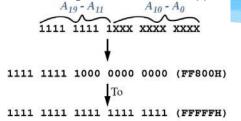
### Memory address decoding

- \* The processor can usually address a memory space that is much larger than the memory space covered by an individual memory chip.
- \* In order to splice a memory device into the address space of the processor, decoding is necessary.
- \* For example, the 8088 issues **20-bit addresses for a total of 1MB of memory address space.**
- \* However, the BIOS on a 2716 EPROM has only 2KB of memory and 11 address pins.
- \* A decoder can be used to decode the additional 9 address pins and allow the EPROM to be placed in any 2KB section of the 1MB address space.



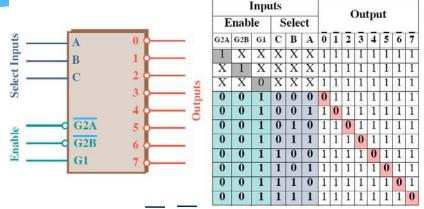
### 20-bit address decoding

\* To determine the address range that a device is mapped into:

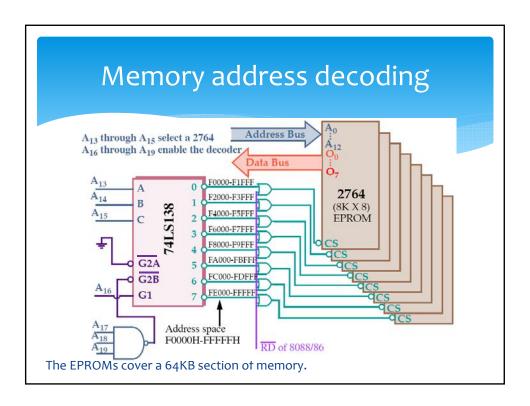


- \* This 2KB memory segment maps into the **reset location** of the 8086/8088 (FFFF0H).
- \* NAND gate decoders are not often used
  - \* Large fan-in NAND gates are not efficient
  - Multiple NAND gate IC's might be required to perform such decoding
  - \* Rather the 3-to-8 Line Decoder (74LS138) is more common.

# 3-to-8 line decoder (74LS138)



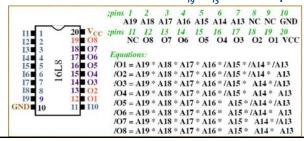
- \* Note that all three Enables ( $\overline{G_2A}$ ,  $G_2B$ , and  $G_1$ ) must be active, e.g. low, low and high, respectively.
- \* Each output of the decoder can be attached to an 2764 EPROM (8K X 8).



# Memory address decoding

#### AMD 16L8 PAL decoder

- \* Commonly used to decode the memory address, particularly for 32-bit addresses generated by the 80386DX and above.
- \* It has 10 fixed inputs (Pins 1-9, 11), two fixed outputs (Pins 12 and 19) and 6 pins that can be **either** (Pins 13-18).
- \* AND/NOR device with logic expressions (outputs) with up to 16 ANDed inputs and 7 ORed product terms.
  - \* Programmed to decode address lines  $A_{19}$   $A_{13}$  onto 8 outputs.



# Next Time

- \* Memory Interfacing
  - \* 8-bit memory interface

STOP

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